

# **DEM-OPA-SSOP-3E Demonstration Fixture**

## 1 Description

The DEM-OPA-SSOP-3E demonstration fixture is a generic, unpopulated printed circuit board (PCB) for triple 2:1 multiplexers in the SSOP-16 package. Figure 1 shows the package pinout supported by this PCB. For more information on specific op amps, as well as good PCB layout techniques, see the individual amplifier data sheets.

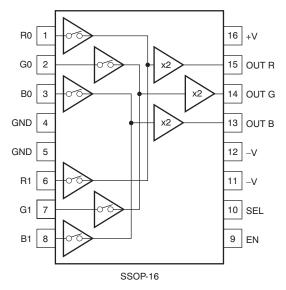


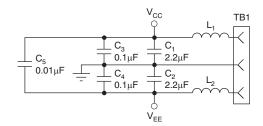
Figure 1. SSOP-16 Package Pinout, Top View



Circuit www.ti.com

### 2 Circuit

The circuit schematic in Figure 2 shows the connections for all possible components. Each configuration uses only some of the components.



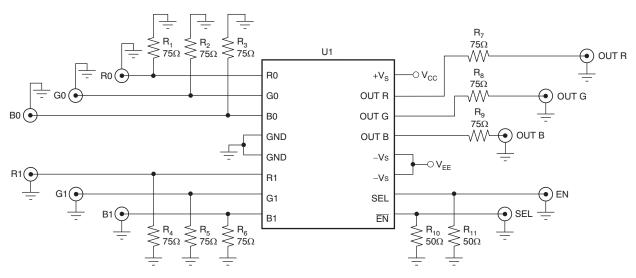


Figure 2. Schematic for DEM-OPA-SSOP-3E

### 3 Components

Components that have RF performance similar to the ones listed in Table 1 may be substituted.  $C_1$  and  $C_2$  need a larger voltage rating for  $\pm 15$ V dual supplies.

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PART	DESCRIPTION
C <sub>1</sub> , C <sub>2</sub>	Tantalum Chip Capacitor, SMD EIA Size 3528, 20V
C <sub>3</sub> , C <sub>4</sub> , C <sub>5</sub>	Multilayer Ceramic Chip Capacitor, SMD 1206, 50V
Bx, Gx, Rx, OUTB, OUTG, OUTR, EN, SEL	SMA or SMB Board Jack (Amphenol 901-144-8) or Side Mount BNC Connection (Trompeter Electronics UCBJE20-1)
L <sub>1</sub> , L <sub>2</sub>	EMI-Suppression Ferrite Chip, SMD 1206 (Steward LI 1206 B 900 R)
TB <sub>1</sub>	Terminal Block, 3.5mm Centers (On-Shore Technology ED555/3DS)
R <sub>7</sub> , R <sub>8</sub> , R <sub>9</sub> , R <sub>10</sub> , R <sub>11</sub>	Metal Film Chip Resistor, SMD 0603 1/8W
R <sub>1-6</sub>	Thin Film Chip Resistor, SMD 0402 1/16W

**Table 1. Component Descriptions** 



www.ti.com Board Layout

 $R_1$  through  $R_9$  set the I/O impedance for the signal chain,  $R_{10}$  and  $R_{11}$  set the input impedance for the select and enable pins, and  $C_1$ ,  $C_2$ ,  $C_3$ ,  $C_4$ , and  $C_5$  are supply bypass capacitors.  $C_5$  is optional; it adds a bypass between the supplies that improves distortion performance for some models.  $L_1$  and  $L_2$  are ferrite chips that can reduce interactions with the power supply at high frequencies. If not desired, they can be replaced with  $0\Omega$  resistors.

For single-supply operation, do not connect  $L_2$ ; otherwise, the  $-V_S$  input to  $TB_1$  would be at ground potential.

### 4 Board Layout

This demonstration fixture is a two-layer PCB. (See Figure 3.) It uses a ground plane on the bottom, and signal and power traces on the top. The ground plane has been opened up around op amp pins sensitive to capacitive loading. Power-supply traces are laid out to keep current loop areas to a minimum. The SMA (or SMB) connectors may be mounted either vertically or horizontally.

The location and type of capacitors used for power-supply bypassing are crucial to high-frequency amplifiers. The tantalum capacitors,  $C_1$  and  $C_2$ , do not need to be as close to pins 11 and 4 on the PCB, and may be shared with other amplifiers.

See the individual op amp data sheet for more information on proper board layout techniques and component selection.

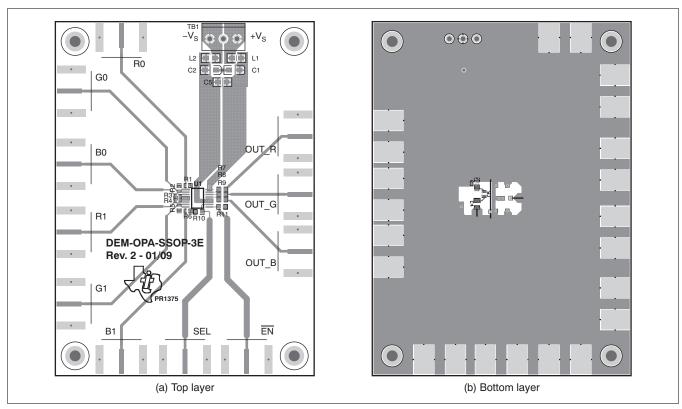


Figure 3. DEM-OPA-SSOP-3E Demonstration Fixture Layout



Measurement Tips www.ti.com

# 5 Measurement Tips

This demonstration fixture, with the component values shown, is designed to operate in a  $50\Omega$  environment; most data sheet plots are obtained under these conditions. It is easy to change the component values for different input and output impedance levels. However, do not use high-impedance probes; they represent a heavy capacitive load to the op amp, and will alter the amplifier response. Instead, use low-impedance ( $\leq 500\Omega$ ) probes with adequate bandwidth. The probe input capacitance and resistance set an upper limit on the measurement bandwidth. If a high-impedance probe must be used, place a  $100\Omega$  resistor on the probe tip to isolate its capacitance from the circuit.

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